



# Test item list

1. <i>Test item list</i> -----	2
2. <i>Temperature rise test</i> -----	3
2. <i>Temp./humidity power on/off Test</i> -----	5
3. <i>Temperature cycle operation test</i> -----	6
4. <i>High temperature storage test</i> -----	7
5. <i>Low temperature storage test</i> -----	8
6. <i>Humidity test</i> -----	9
7. <i>Cold start and hot start test</i> -----	10

## Test Configuration:

Num	Item	Spec
1.	Mounting Chassis:	FWS-7300
	1. PCB / CPU	FWB-7300 A1.0 (BIOS: 0.B) / Intel Pentium M 1.8GHz
	3. Memory	Transcend DDR2-667 1GB / ELPIDA E5108AJBG-6E-E * 1 ADATA DDR2-667 1GB / ADATA AD29608A8A-3EG80818 * 1
	4. CFD	PQI 32MB (for DOS mode Power on/off test)
	5. SATA HDD	Seagate ST3160815AS / 160GB
	6. Test Software	Windows XP / Run PassMark Burn In Test 4.0 Pro
2.	Power Supply	FSP FSP150-50LE

# Temperature rise test

**Test Date:** 10-24-2008

**Test Product:** FWS-7300

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference EN 61131-2(94), UL508 (94)

**Temperature Measurement:**

40 Channel Thermal Recorder:

YOKOGAWA Inc,

Model: DA100-13-1D

Date of Calibration: 12/13/07

Serial Number: 12A323190

**Test Condition:**

Ambient temperature: 40dC

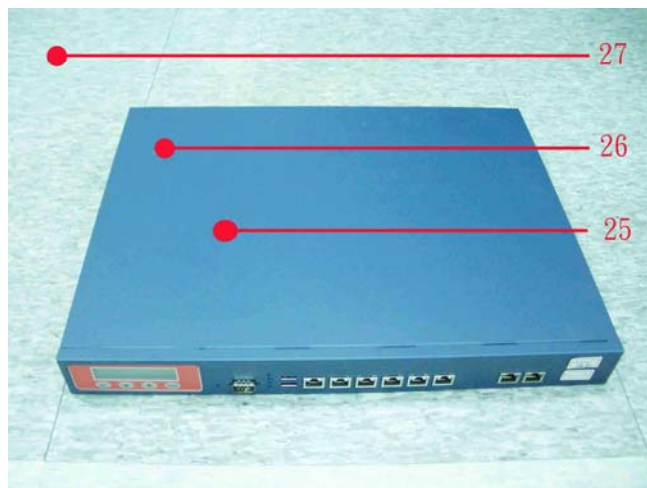
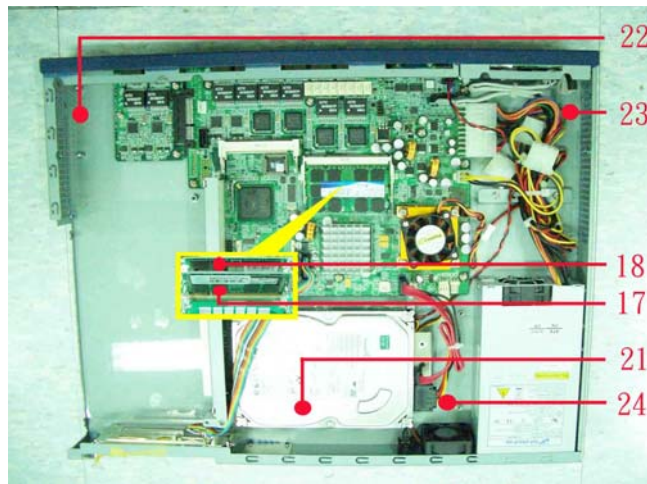
Continuous running till thermal stability (within less than 1°C)

**Test Software:**

Windows XP / Run PassMark Burn In Test 4.0 Pro

**Terminal Recorder:**

Measuring Thermal Couple Position :



# Temperature rise test

## Thermal profile data:

### FWS-7300

Point	Temp. Stage(°C)	Spec	40	25
<b>FWB-7300</b>				
1. CPU: Intel Celeron M / 600MHz		100	66.2	51.2
2. U3 - (TF) Chipset Alviso 910GMLE.Intel.QG82910GMLE SLA9L		99	68.3	53.3
3. U8 - (TF) Chipset ICH6M.Intel.NH82801FBM SL89K B2		95	80.5	65.5
4. U12 - (TF) IMVP4 Single Phase PWM.Intersil.ISL6218CVZ		100	57.7	42.7
5. L12 - (TF) COIL.1.2uH.TRIO.LG-12AM11C03		105	57.1	42.1
6. U21 - (TF) Power Controller.for Dual Channel DDR.Intersil.ISL6537CRZ		100	54.4	39.4
7. U20 - (TF) REG.SMD.TO-263 5A Linear Regulator.ATC.AP-1084KLA		125	67.4	52.4
8. U18 - (TF) GigaBit Ethernet Chipset.INTEL.LU82541PI		95	60.7	45.7
9. U19 - (TF) GigaBit Ethernet Chipset.INTEL.LU82541PI		95	61.8	46.8
10.U22 - (TF) GigaBit Ethernet Chipset.INTEL.LU82541PI		95	61.6	46.6
11.U23 - (TF) GigaBit Ethernet Chipset.INTEL.LU82541PI		95	62.8	47.8
12.U24 - (TF) PCI-E GigaBit Ethernet Chipset.Intel.WG82574L		95	66.7	51.7
13.U25 - (TF) PCI-E GigaBit Ethernet Chipset.Intel.WG82574L		95	65.3	50.3
14.BC78 - (TF) MCC.0.1uF.16V.10%.X7R.0402 SMD		125	59.6	44.6
15.U11 - (TF) CLOCK GENERATOR.ICS.ICS954206AGLFT		95	83.4	68.4
16.U13 - (TF) Clock Output Buffer.ICS.ICS9112M-16LF-T		95	65.2	50.2
17. Memory - 1		70	57.8	42.8
18. Memory - 2		70	58.6	43.6
<b>PER-C34L</b>				
19. U1 - (TF) PCI-E GigaBit Ethernet Chipset.Intel.WG82574L		95	66.2	51.2
20. U3 - (TF) PCI-E GigaBit Ethernet Chipset.Intel.WG82574L		95	64.6	49.6
21.HDD		60	50.9	35.9
22.Control Box Internal Air Temperature - 1		N/A	40.2	25.2
23.Control Box Internal Air Temperature - 2		N/A	40.6	25.6
24.Power Supply - Ambient Temperature		50	51.5	36.5
25.Control Box External Surface - 1		N/A	48.1	33.1
26.Control Box External Surface - 2		N/A	42.5	27.5
27.Chamber Air Temperature		N/A	40.1	25.1
<b>Any Tm value showed in red words which meaning the value over the Tc + 5 degree C of this device specification.</b>				

## Sample Configuration & Quantity Under Test:

Quantity: 1 (FWS-7300)

## Test Result:

No problem was found during the temperature rise operation test.

**Test Date:** 07-11~12-2008

**Test Product:** FWB-7300 A0.1

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-30 Testing procedures  
Test Db: Damp Heat Test

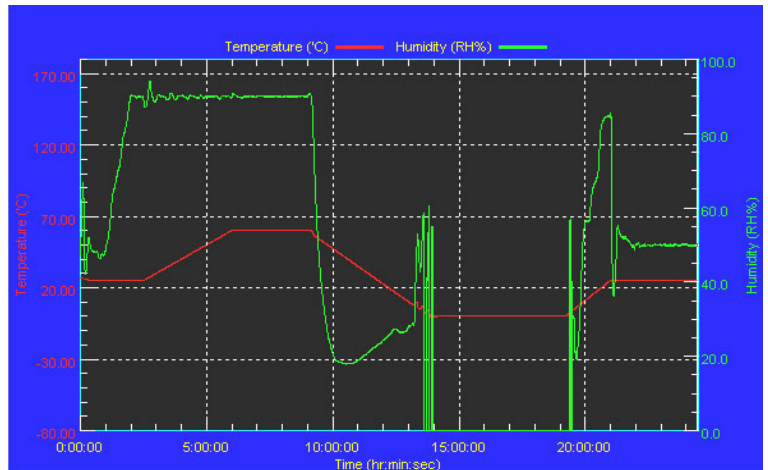
**Test Equipment:**  
Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-D7S-100+1 N2  
Date of Calibration: 12/13/07  
Serial Number: 3898

**Temperature & Humidity Power On/Off Test:**

**Testing Specification:**

Step	Temperature (°C)	Humidity (%RH)	Duration (HH:MM)
1	25	50	00:30
2	25	50	00:30
3	25	90	01:00
4	25	90	00:30
5	60	90	03:30
6	60	90	03:00
7	0	0	04:50
8	0	0	05:23
9	25	50	01:47
10	25	50	03:00

**Test Curve:**



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (FWB-7300)

**Test Result:**

No problem was found during the temperature & humidity power on/off test.

# Temperature cycle test

**Test Date:** 10-20~22-2008

**Test Product:** FWS-7300

**Test Site:** AAEON QA Internal Lab.

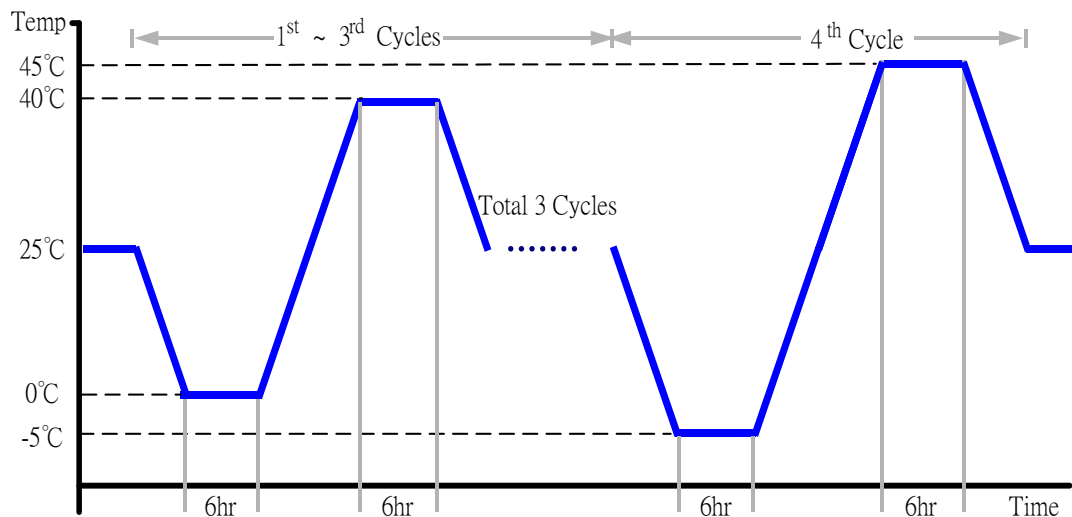
**Test Standard:** Reference IEC68-2-14 Testing procedures  
Test N: Change of temperature Test

**Test Equipment:**

Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-A4C-100  
Date of Calibration: 06/18/08  
Serial Number: 3188

**Test Condition:**

1. Test Low Temperature: 0°C (1~3 cycles)  
-5°C (4<sup>th</sup> cycle)
2. Test High Temperature: 40°C (1~3 cycles)  
45°C (4<sup>th</sup> cycle)
3. Test dwell time: 6Hrs
4. Temperature slope: 2°C/min
5. Test cycle: 4 cycles
6. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (FWS-7300)

**Test Result:**

No problem was found during the temperature operation cycle test.

# High temperature storage test

**Test Date:** 10-15~17-2008

**Test Product:** FWS-7300

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-2 Testing procedures  
Test Bb: Dry Heat Test (Non-operation)

**Test Equipment:**

Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.

Model: THS-A4C-100

Date of Calibration: 06/18/08

Serial Number: 3188

**Testing Item:**

1. Test Temperature: 60°C
2. Test Times: 48Hrs
3. Test Software: Windows XP / Run PassMark Burn In Test 4.0 Pro
4. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (FWS-7300)

**Test Result:**

No problem was found after the high temperature storage test.

**Test Date:** 10-10~12-2008

**Test Product:** FWS-7300

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-1 Testing procedures  
Test Ab: Cold Test (Non-operation)

**Test Equipment:**

Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.

Model: THS-A4C-100

Date of Calibration: 06/18/08

Serial Number: 3188

**Testing Item:**

1. Test Temperature: -20°C
2. Test Times: 48Hrs
3. Test Software: Windows XP / Run PassMark Burn In Test 4.0 Pro
4. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (FWS-7300)

**Test Result:**

No problem was found after the low temperature storage test.



**Test Date:** 10-17~19-2008

**Test Product:** FWS-7300

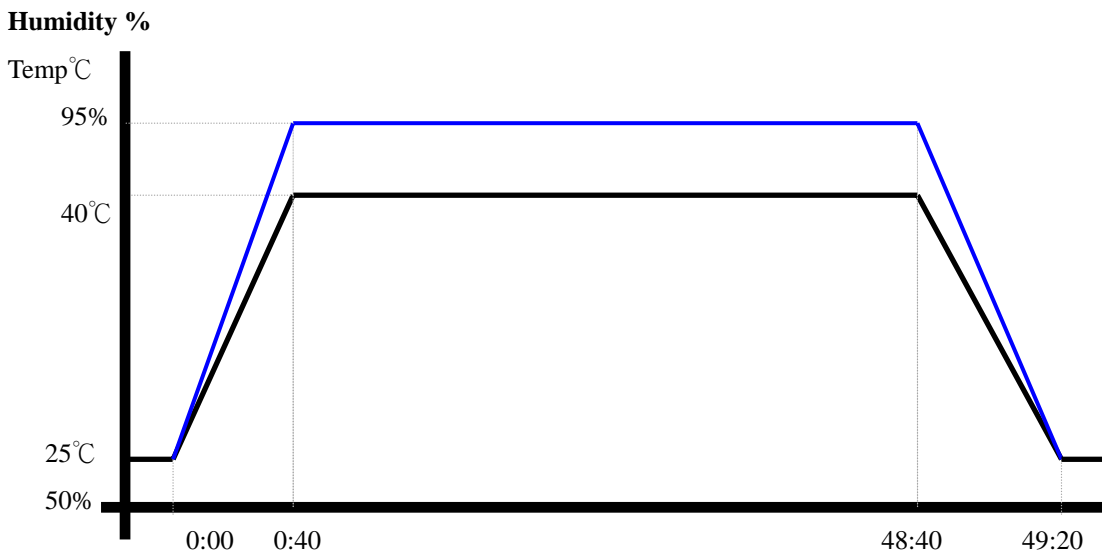
**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-3 Testing procedures  
Test Ca: Damp heat, steady state (Non-operation)

**Test Equipment:**  
Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-A4C-100  
Date of Calibration: 06/18/08  
Serial Number: 3188

**Testing Item:**

1. Test Temperature: 40°C
2. Test Humidity: 95%RH
3. Test Times: 48Hrs
4. Test Software: Windows XP / Run PassMark Burn In Test 4.0 Pro
5. Test Environment Curve:



**Sample Configuration & Quantity Under Test:**

Quantity: 1 (FWS-7300)

**Test Result:**

No problem was found after the humidity storage test.

# Cold start and hot start test

**Test Date:** 10-22~23-2008

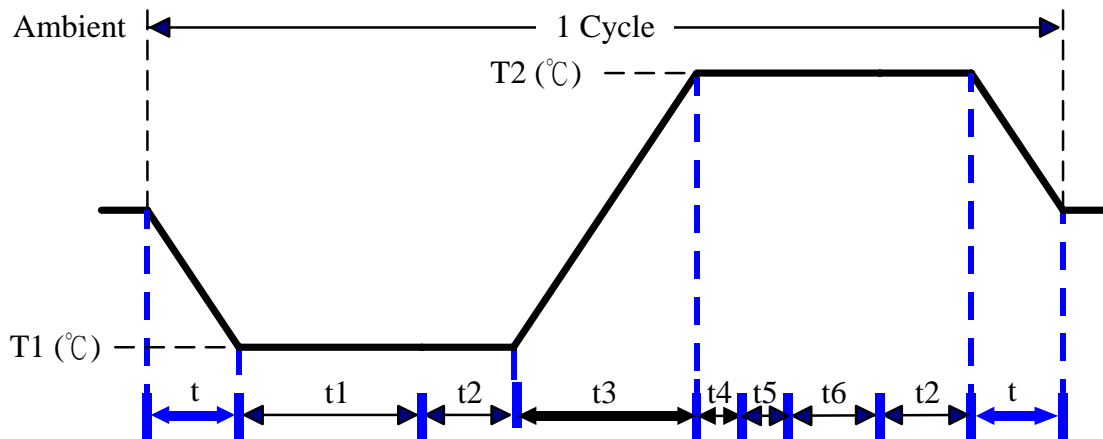
**Test Product:** FWS-7300

**Test Site:** AAEON QA Internal Lab.

**Test Standard:** Reference IEC 68-2-14 Testing procedures  
Test N: Change of temperature Test

**Test Equipment:**  
Programmable Temperature & Humidity Chamber  
K.SON. INS. TECH. CORP.  
Model: THS-A4C-100  
Date of Calibration: 06/18/08  
Serial Number: 3188

**Test Condition:**



Parameters	Description
T1	-5°C
T2	45°C
t1	4 hrs
t2, t6	2 hrs
t4, t5	1hrs
t, t3	2°C/min
n (Cycle)	1

t = temprature slope  
t , t1, t6: Power Off  
t2: Power on/off test 10 times (on 2 min / off 5min)  
t3, t4: Run PassMark Burn In Test  
t5: Win XP Software restart test 3 times  
Test Software:Windows XP

**Test Result:**

- a. No problem was found during the cold start test.
- b. No problem was found during the hot start test.